芯伯乐®
XINBOLE

Product Specification

XBLW SN74LS85

4-bit Magnitude Comparator

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Description

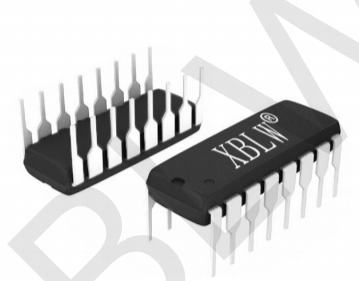
The SN74LS85 is a 4-bit magnitude comparator that can be expanded to almost any length. They perform comparison of two 4-bit binary, BCD or other monotonic codes and present the three possible magnitude results at the outputs ($Q_{A>B}$, $Q_{A=B}$ and $Q_{A<B}$). The 4-bit inputs are weighted (A0 to A3 and B0 to B3), where A3 and B3 are the most significant bits. For proper compare operation the expander inputs ($I_{A>B}$, $I_{A=B}$ and $I_{A<B}$) to the least significant position must be connected as follows: $I_{A<B}$=$I_{A>B}$=LOW and $I_{A=B}$=HIGH. For words greater than 4-bits, units can be cascaded by connecting outputs $Q_{A>B}$, $Q_{A=B}$ and $Q_{A<B}$ to the corresponding inputs of the significant comparator. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC}.

Features

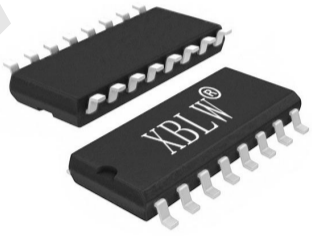
- Wide supply voltage range from 2.0 to 6.0V
- CMOS low power dissipation
- CMOS Input levels
- Specified from -20°C to +85°C
- Packaging information: DIP16/SOP16/TSSOP16

Applications

- Process controllers
- Servo-motor control



DIP-16



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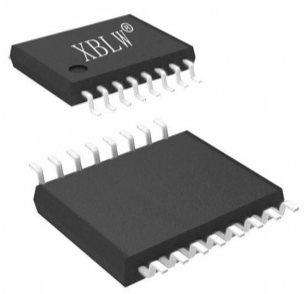


TSSOP-16

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LS85N	DIP-16	74LS85N	Tube	1000Pcs/Box
XBLW SN74LS85DTR	SOP-16	74LS85	Tape	2500Pcs/Reel
XBLW SN74LS85TDTR	TSSOP-16	74LS85	Tape	3000Pcs/Reel

Block Diagram

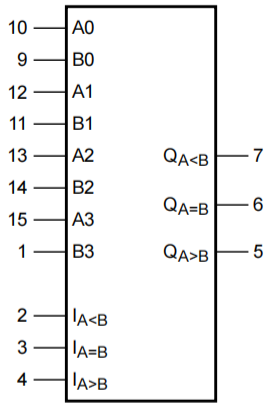


Figure 1. Logic symbol

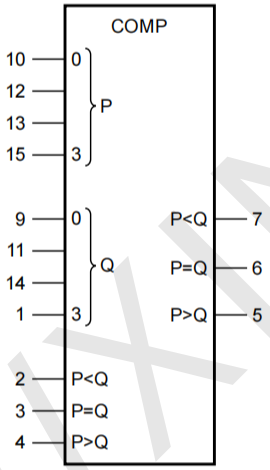


Figure 2. IEC logic symbol

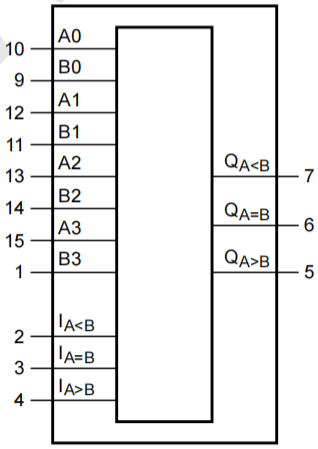


Figure 3. Functional diagram

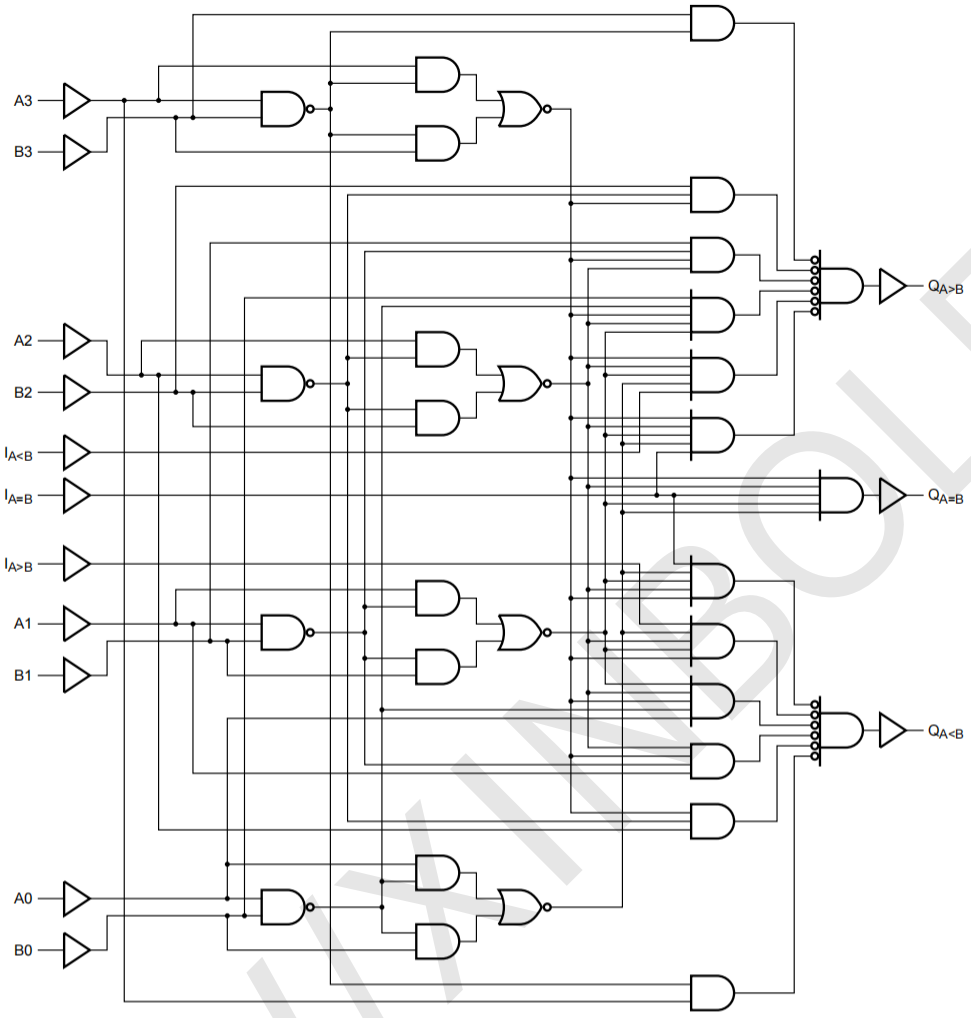
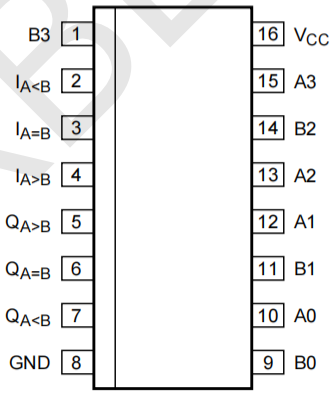
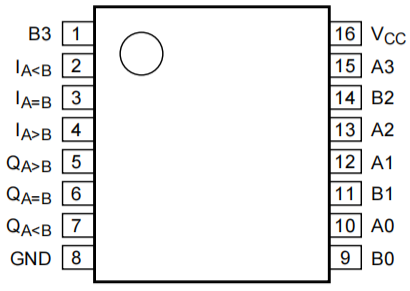


Figure 4. Logic diagram

Pin Configurations



DIP 16 SOP-16



TSSOP-16

Pin Description

Pin No.	Pin Name	Description
1	B3	word B input
2	$I_{A<B}$	A<B expansion input
3	$I_{A=B}$	A=B expansion input
4	$I_{A>B}$	A>B expansion input
5	$Q_{A>B}$	A>B output
6	$Q_{A=B}$	A=B output
7	$Q_{A<B}$	A<B output
8	GND	ground (0V)
9	B0	word B input
10	A0	word A input
11	B1	word B input
12	A1	word A input
13	A2	word A input
14	B2	word B input
15	A3	word A input
16	V_{CC}	supply voltage

Function Table

Comparing input				Cascading input			Output		
A3, B3	A2, B2	A1, B1	A0, B0	$I_{A>B}$	$I_{A<B}$	$I_{A=B}$	$Q_{A>B}$	$Q_{A<B}$	$Q_{A=B}$
A3>B3	X	X	X	X	X	X	H	L	L
A3<B3	X	X	X	X	X	X	L	H	L
A3=B3	A2>B2	X	X	X	X	X	H	L	L
A3=B3	A2<B2	X	X	X	X	X	L	H	L
A3=B3	A2=B2	A1>B1	X	X	X	X	H	L	L
A3=B3	A2=B2	A1<B1	X	X	X	X	L	H	L
A3=B3	A2=B2	A1=B1	A0>B0	X	X	X	H	L	L
A3=B3	A2=B2	A1=B1	A0<B0	X	X	X	L	H	L
A3=B3	A2=B2	A1=B1	A0=B0	H	L	L	H	L	L
A3=B3	A2=B2	A1=B1	A0=B0	L	H	L	L	H	L
A3=B3	A2=B2	A1=B1	A0=B0	L	L	H	L	L	H
A3=B3	A2=B2	A1=B1	A0=B0	X	X	H	L	L	H
A3=B3	A2=B2	A1=B1	A0=B0	H	H	L	L	L	L
A3=B3	A2=B2	A1=B1	A0=B0	L	L	L	H	H	L

Note: H=HIGH voltage level; L=LOW voltage level; X=don't care.

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Max.	Unit
supply voltage	V_{CC}	-		-0.5	+7.0	V
input clamping current	I_{IK}	V_I < -0.5V or V_I > V_{CC}+0.5V		-	±20	mA
output clamping current	I_{OK}	V_O < -0.5V or V_O > V_{CC}+0.5V		-	±20	mA
output current	I_O	-0.5V < V_O < V_{CC}+0.5V		-	±25	mA
supply current	I_{CC}	-		-	50	mA
ground current	I_{GND}	-		-50	-	mA
storage temperature	T_{stg}	-		-65	+150	℃
total power dissipation	P_{tot}	-		-	500	mW
soldering temperature	T_L	10s	DIP	245		℃
			SOP	250		

Note:

[1] For DIP16 packages: above 70℃ the value of P_{tot} derates linearly with 12mW/K.

[2] For SOP16 packages: above 70℃ the value of P_{tot} derates linearly with 8mW/K.

[3] For (T)SSOP16 packages: above 60℃ the value of P_{tot} derates linearly with 5.5mW/K.

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
input transition rise and fall rate	$\Delta t/\Delta V$	V_{CC}=2.0V	-	-	625	ns/V
		V_{CC}=4.5V	-	1.67	139	ns/V
		V_{CC}=6.0V	-	-	83	ns/V
ambient temperature	T_{amb}	-	-20	-	+85	℃

Electrical Characteristics

DC Characteristics 1

(T_{amb}=25℃, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	V_{CC}=2.0V		1.5	1.2	-	V
		V_{CC}=4.5V		3.15	2.4	-	V
		V_{CC}=6.0V		4.2	3.2	-	V
LOW-level input voltage	V_{IL}	V_{CC}=2.0V		-	0.8	0.5	V
		V_{CC}=4.5V		-	2.1	1.35	V
		V_{CC}=6.0V		-	2.8	1.8	V
HIGH-level output voltage	V_{OH}	V_I=V_{IH} or V_{IL}	I_O=-20uA; V_{CC}=2.0V	1.9	2.0	-	V
			I_O=-20uA; V_{CC}=4.5V	4.4	4.5	-	V
			I_O=-20uA; V_{CC}=6.0V	5.9	6.0	-	V
			I_O=-4.0mA; V_{CC}=4.5V	3.98	4.32	-	V
			I_O=-5.2mA; V_{CC}=6.0V	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	V_I=V_{IH} or V_{IL}	I_O=20uA; V_{CC}=2.0V	-	0	0.1	V
			I_O=20uA; V_{CC}=4.5V	-	0	0.1	V
			I_O=20uA; V_{CC}=6.0V	-	0	0.1	V
			I_O=4.0mA; V_{CC}=4.5V	-	0.15	0.26	V
			I_O=5.2mA; V_{CC}=6.0V	-	0.16	0.26	V
input leakage current	I_I	V_I=V_{CC} or GND; V_{CC}=6.0V		-	-	±0.1	uA
supply current	I_{CC}	V_I=V_{CC} or GND; I_O=0A; V_{CC}=6.0V		-	-	8.0	uA
input capacitance	C_I	-		-	3.5	-	pF

DC Characteristics 2

(T_{amb}=-20℃ to +85℃, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	V_{CC}=2.0V		1.5	-	-	V
		V_{CC}=4.5V		3.15	-	-	V
		V_{CC}=6.0V		4.2	-	-	V
LOW-level input voltage	V_{IL}	V_{CC}=2.0V		-	-	0.5	V
		V_{CC}=4.5V		-	-	1.35	V
		V_{CC}=6.0V		-	-	1.8	V
HIGH-level output voltage	V_{OH}	V_I=V_{IH} or V_{IL}	I_O=-20uA; V_{CC}=2.0V	1.9	-	-	V
			I_O=-20uA; V_{CC}=4.5V	4.4	-	-	V
			I_O=-20uA; V_{CC}=6.0V	5.9	-	-	V
			I_O=-4.0mA; V_{CC}=4.5V	3.84	-	-	V
			I_O=-5.2mA; V_{CC}=6.0V	5.34	-	-	V
LOW-level output voltage	V_{OL}	V_I=V_{IH} or V_{IL}	I_O=20uA; V_{CC}=2.0V	-	-	0.1	V
			I_O=20uA; V_{CC}=4.5V	-	-	0.1	V
			I_O=20uA; V_{CC}=6.0V	-	-	0.1	V
			I_O=4.0mA; V_{CC}=4.5V	-	-	0.33	V
			I_O=5.2mA; V_{CC}=6.0V	-	-	0.33	V
input leakage current	I_I	V_I=V_{CC} or GND; V_{CC}=6.0V		-	-	±1.0	uA
supply current	I_{CC}	V_I=V_{CC} or GND; I_O=0A; V_{CC}=6.0V		-	-	80	uA

AC Characteristics 1

(T_{amb}=25℃, GND =0V, C_L=50pF, unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
propagation delay	t_{pd}	An, Bn to $Q_{A>B}$; An, Bn to $Q_{A<B}$; see Figure 6[1]	V_{CC}=2.0V	-	63	195	ns
			V_{CC}=4.5V	-	23	39	ns
			V_{CC}=5.0V; C_L=15pF	-	20	-	ns
			V_{CC}=6.0V	-	18	33	ns
		An, Bn to $Q_{A=B}$; see Figure 6	V_{CC}=2.0V	-	58	175	ns
			V_{CC}=4.5V	-	21	35	ns
			V_{CC}=5.0V; C_L=15pF	-	18	-	ns
			V_{CC}=6.0V	-	17	30	ns
		$I_{A=B}$ or $I_{A>B}$ to $Q_{A<B}$; $I_{A<B}$ or $I_{A=B}$ to $Q_{A>B}$; see Figure 6	V_{CC}=2.0V	-	50	140	ns
			V_{CC}=4.5V	-	18	28	ns
			V_{CC}=5.0V; C_L=15pF	-	15	-	ns
			V_{CC}=6.0V	-	14	24	ns
		$I_{A=B}$ to $Q_{A=B}$; see Figure 6	V_{CC}=2.0V	-	39	120	ns
			V_{CC}=4.5V	-	14	24	ns
			V_{CC}=5.0V; C_L=15pF	-	11	-	ns
			V_{CC}=6.0V	-	11	20	ns
transition time	t_t	see Figure 6[2]	V_{CC}=2.0V	-	19	75	ns
			V_{CC}=4.5V	-	7	15	ns
			V_{CC}=6.0V	-	6	13	ns
power dissipation capacitance	C_{PD}	per package; V_I=GND to V_{CC}[3]		-	18	-	pF

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.

[2] t_t is the same as t_{THL} and t_{TLH}.

[3] C_{PD} isused to determine the dynamic power dissipation (P_D in uW).

$P_D=C_{PD}\times V_{CC}^2\times f_i+\Sigma(C_L\times V_{CC}^2\times f_o)$ where:

f_i=input frequency in MHz; f_o=output frequency in MHz;

C_L=output load capacitance in pF;

V_{CC}=supply voltage in V;

$\Sigma(C_L\times V_{CC}^2\times f_o)$=sum of outputs.

AC Characteristics 2

(T_{amb}=-20℃ to +85℃, GND =0V, C_L=50pF, unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
propagation delay	t_{pd}	An, Bn to $Q_{A>B}$; An, Bn to $Q_{A<B}$; see Figure 6[1]	V_{CC}=2.0V	-	-	245	ns
			V_{CC}=4.5V	-	-	49	ns
			V_{CC}=6.0V	-	-	42	ns
		An, Bn to $Q_{A=B}$; see Figure 6	V_{CC}=2.0V	-	-	220	ns
			V_{CC}=4.5V	-	-	44	ns
			V_{CC}=6.0V	-	-	37	ns
		$I_{A=B}$ or $I_{A>B}$ to $Q_{A<B}$; $I_{A<B}$ or $I_{A=B}$ to $Q_{A>B}$; see Figure 6	V_{CC}=2.0V	-	-	175	ns
			V_{CC}=4.5V	-	-	35	ns
			V_{CC}=6.0V	-	-	30	ns
		$I_{A=B}$ to $Q_{A=B}$; see Figure 6	V_{CC}=2.0V	-	-	150	ns
			V_{CC}=4.5V	-	-	30	ns
			V_{CC}=6.0V	-	-	26	ns
transition time	t_t	see Figure 6[2]	V_{CC}=2.0V	-	-	95	ns
			V_{CC}=4.5V	-	-	19	ns
			V_{CC}=6.0V	-	-	16	ns

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.

[2] t_t is the same as t_{THL} and t_{TLH}.

Testing Circuit

AC Testing Circuit

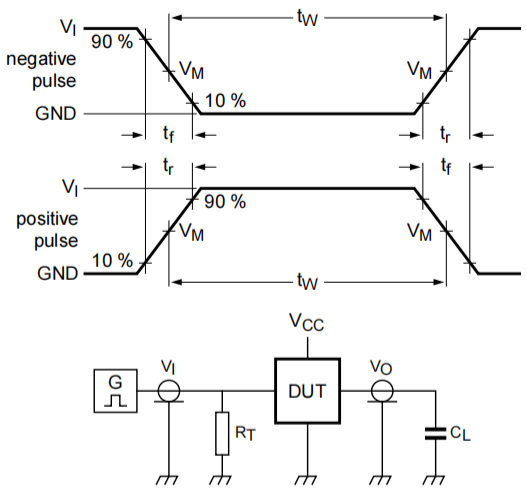


Figure 5. Test circuit for measuring switching times

Definitions for test circuit:

C_L=Load capacitance including jig and probe capacitance.

R_T=Termination resistance should be equal to the output impedance Z_o of the pulse generator.

AC Testing Waveforms

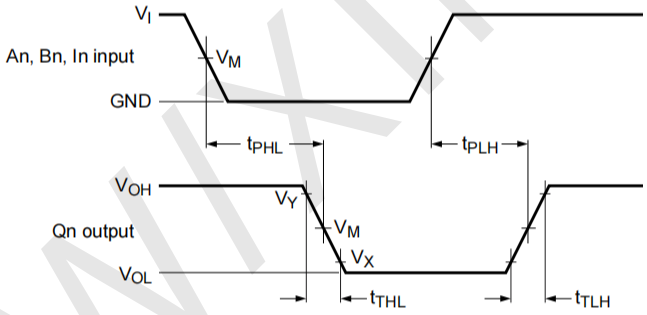


Figure 6. Word A inputs (An), word B inputs (Bn) and expansion inputs (In) to the outputs (Qn) propagation delays and the output transition times

Measurement Points

Type	Input		Output		
	V_I	V_M	V_M	V_X	V_Y
SN74LS85	V_{CC}	$0.5\times V_{CC}$	$0.5\times V_{CC}$	$0.1\times V_{CC}$	$0.9\times V_{CC}$

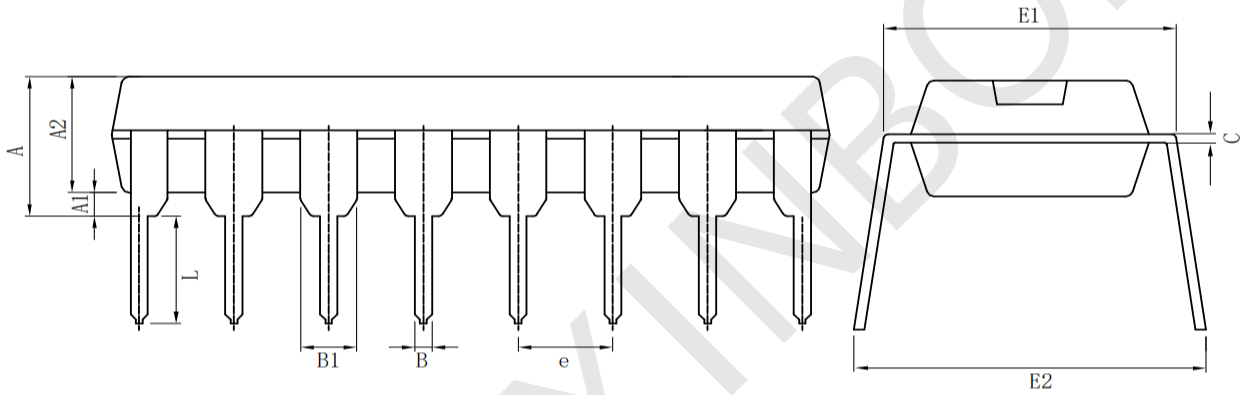
Test Data

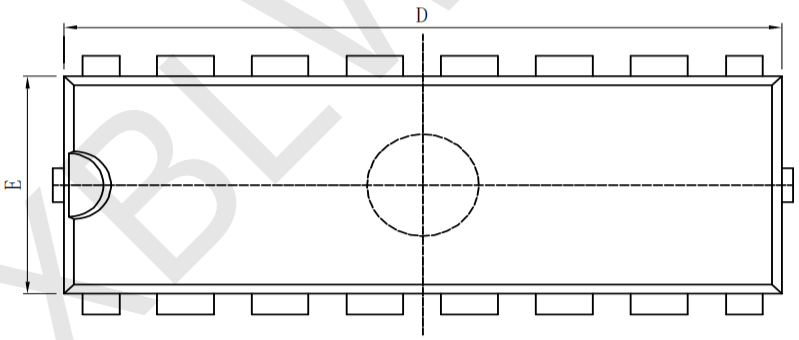
Type	Input		Load	Test
	V_I	t_r ,t_f	C_L	
SN74LS85	V_{CC}	6ns	15pF, 50pF	t_{PHL}, t_{PLH}

Package Information

· DIP-16

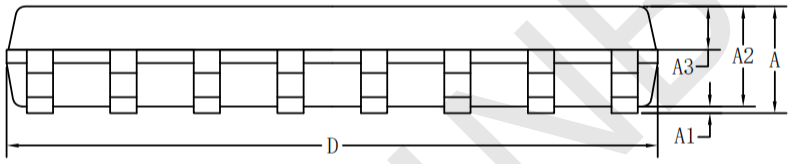
Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	3.710	4.310	A	0.146	0.170
A1	0.510		A1	0.020	
A2	3.200	3.600	A2	0.126	0.142
B	0.380	0.570	B	0.015	0.022
B1	1.524(BSC)		B1	0.060(BSC)	
C	0.204	0.360	C	0.008	0.014
D	18.80	19.20	D	0.740	0.756
E	6.200	6.600	E	0.244	0.260
E1	7.320	7.920	E1	0.288	0.312
e	2.540(BSC)		e	0.100(BSC)	
L	3.000	3.600	L	0.118	0.142
E2	8.400	9.000	E2	0.331	0.354

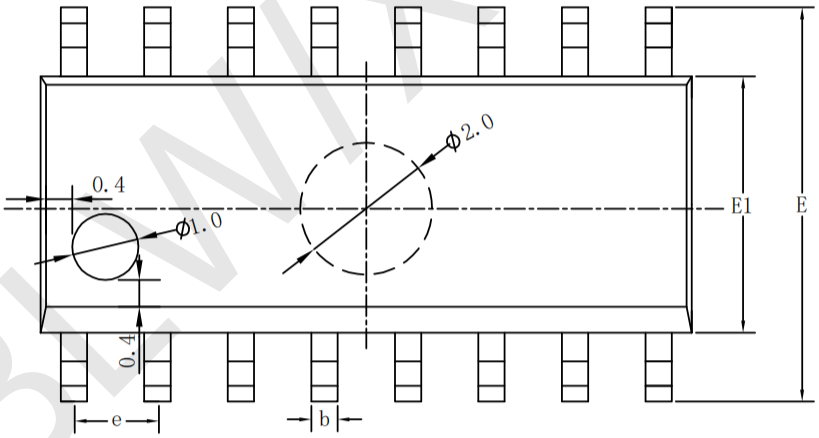


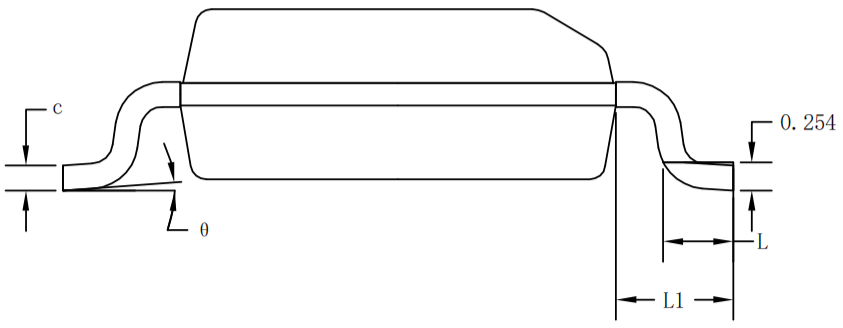


· SOP-16

Size / Symbol	Dimensions In Millimeters			Size / Symbol	Dimensions In Inches		
	Min(mm)	Nom(mm)	Max(mm)		Min(in)	Nom(in)	Max(in)
A	1.500	1.600	1.700	A	0.059	0.063	0.067
A1	0.100	0.150	0.250	A1	0.004	0.006	0.010
A2	1.400	1.450	1.500	A2	0.055	0.057	0.059
A3	0.600	0.650	0.700	A3	0.024	0.026	0.028
b	0.300	0.400	0.500	b	0.012	0.016	0.020
c	0.150	0.200	0.250	c	0.006	0.008	0.010
D	9.800	9.900	10.00	D	0.386	0.390	0.394
E	5.800	6.000	6.200	E	0.228	0.236	0.244
E1	3.850	3.900	3.950	E1	0.152	0.154	0.156
e		1.27(BSC)		e		0.050(BSC)	
L	0.500	0.600	0.700	L	0.020	0.024	0.028
L1		1.05(BSC)		L1		0.041(BSC)	
θ	0°	4°	8°	θ	0°	4°	8°

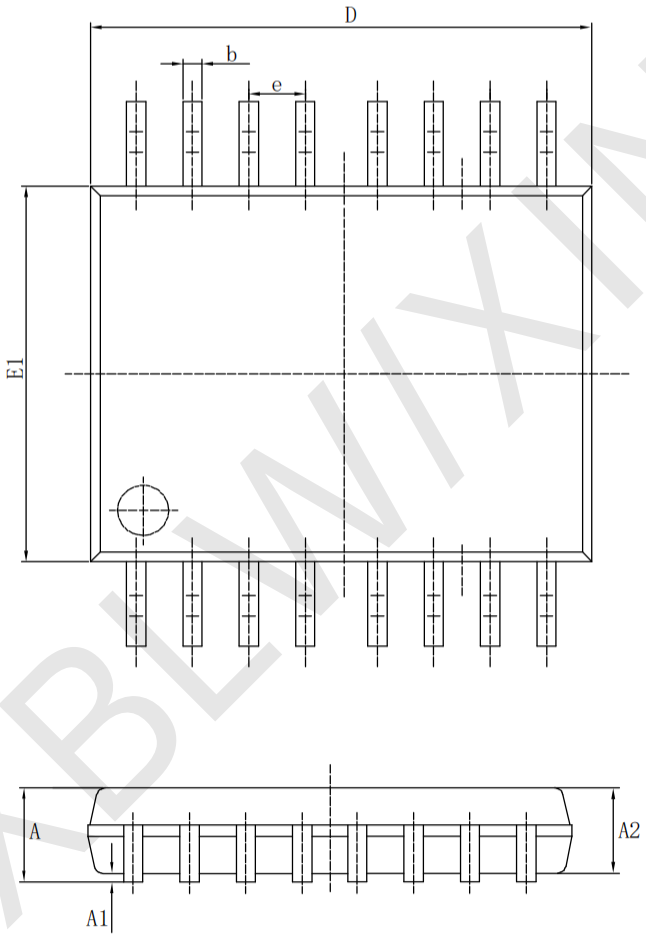


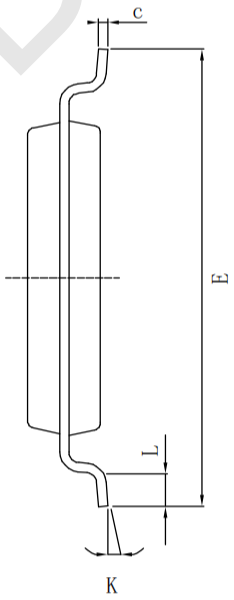




· TSSOP-16

Size / Symbol	Dimensions In Millimeters		Size / Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A		1.200	A		0.047
A1	0.050	0.150	A1	0.002	0.006
A2	0.800	1.050	A2	0.031	0.041
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.0089
D	4.900	5.100	D	0.193	0.201
E	6.200	6.600	E	0.244	0.260
E1	4.300	4.480	E1	0.169	0.176
e	0.65(BSC)		e	0.0256(BSC)	
K	0°	8°	K	0°	8°
L	0.450	0.750	L	0.018	0.030





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